

SN5423, SN5425, SN7423, SN7425 DUAL 4-INPUT NOR GATES WITH STROBE

SDLS082

DECEMBER 1983—REVISED MARCH 1988

- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

These devices contain dual 4-input positive NOR gates with strobe. They perform the Boolean function:

$$Y = \overline{G(A+B+C+D)}$$

(with 1X and 1X̄ of '23 left open).

The SN5423 and the SN5425 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN7423 and the SN7425 are characterized for operation from 0°C to 70°C.

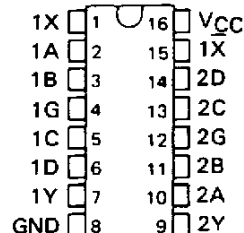
FUNCTION TABLE

INPUTS					OUTPUT
A	B	C	D	G	Y
H	X	X	X	H	L
X	H	X	X	H	L
X	X	H	X	H	L
X	X	X	H	H	L
L	L	L	L	X	H
X	X	X	X	L	H

Expander inputs are open,
H = high level, L = low level, X = irrelevant

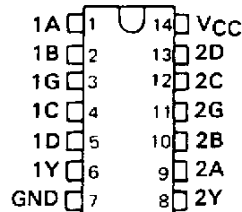
SN5423 . . . J OR W PACKAGE
SN7423 . . . N PACKAGE

(TOP VIEW)

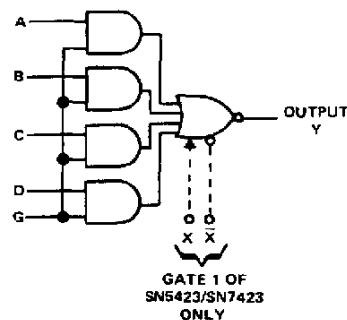


SN5425 . . . J OR W PACKAGE
SN7425 . . . N PACKAGE

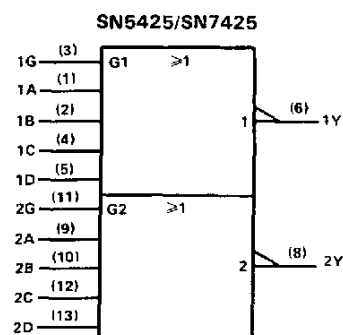
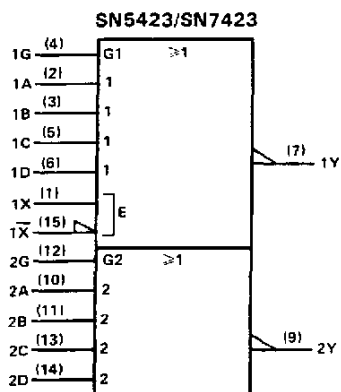
(TOP VIEW)



logic diagram



logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers are for J, N, or W packages.

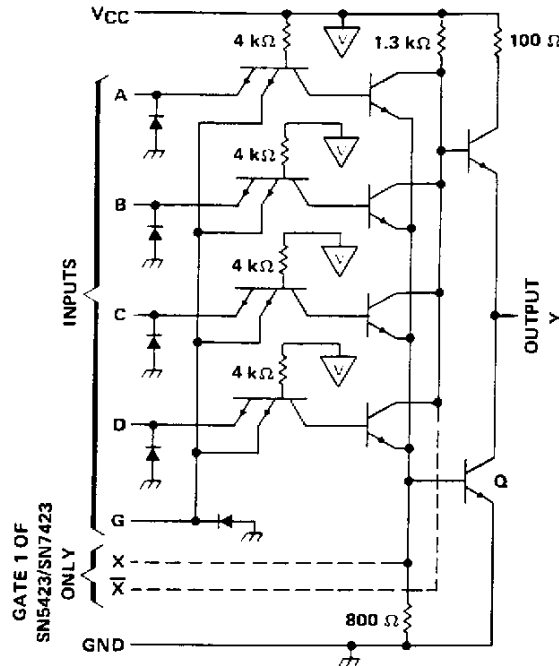
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS


POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN5423, SN5425, SN7423, SNSN7425 DUAL 4-INPUT NOR GATES WITH STROBE

schematic (each gate)



- NOTES: A. Component values shown are nominal.
 B. Both expander inputs are used simultaneously for expanding.
 C. If expander is not used leave X and X' open.
 D. A total of four expander gates can be connected to the expander inputs.

 - VCC bus

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Intermitter voltage (see Note 2)	5.5 V
Operating free-air temperature range: SN5423, SN5425 Circuits	-55°C to 125°C
SN7423, SN7425 Circuits	0°C to 70°C
Storage temperature range	-65°C to 150°C

- NOTES: 1. Voltage values, except intermitter voltage, are with respect to network ground terminal.
 2. This is the voltage between two emitters of a multiple-emitter transistor.

recommended operating conditions

		'23, '25			UNIT
		MIN	NOM	MAX	
V_{CC} Supply voltage	54 Family	4.5	5	5.5	V
	74 Family	4.75	5	5.25	
V_{IH} High-level input voltage		2			V
V_{IL} Low-level input voltage		0.8			V
I_{OH} High-level output current		-0.8			mA
I_{OL} Low-level output current	54 Family	16			mA
	74 Family	16			
T_A Operating free-air temperature range	54 Family	-55	125		°C
	74 Family	0	70		

The '23 is designed for use with up to four '60 expanders.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN5423, SN5425, SN7423, SN7425 DUAL 4-INPUT NOR GATES WITH STROBE

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT	
V_I		$V_{CC} = \text{MIN}$, $I_I = -12 \text{ mA}$			-1.5	V	
V_{OH}		$V_{CC} = \text{MIN}$, $V_{IL} = 0.8 \text{ V}$, $I_{OH} = -0.8 \text{ mA}$	2.4	3.4		V	
V_{OL}		$V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $I_{OL} = 16 \text{ mA}$		0.2	0.4	V	
I_I		$V_{CC} = \text{MAX}$, $V_I = 5.5 \text{ V}$			1	mA	
I_{IH}	data inputs	$V_{CC} = \text{MAX}$, $V_I = 2.4 \text{ V}$			40	μA	
	strobe inputs				160		
I_{IL}	data inputs	$V_{CC} = \text{MAX}$, $V_I = 0.4 \text{ V}$			-1.6	mA	
	strobe inputs				-6.4		
$I_{OS}§$		$V_{CC} = \text{MAX}$	54 Family		-20	-55	mA
			74 Family		-18	-55	
I_{CCH}		$V_{CC} = \text{MAX}$, All inputs at 0 V			8	16	mA
I_{CCL}		$V_{CC} = \text{MAX}$, All inputs at 5 V			10	19	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type. Expander inputs X and \bar{X} are open.

‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time.

electrical characteristics (SN5423 circuits) using expander inputs, $V_{CC} = 4.5 \text{ V}$, $T_A = -55^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$I_{\bar{X}}$	Expander current $V_{X\bar{X}} = 0.4 \text{ V}$, $I_{OL} = 16 \text{ mA}$			-3.5	mA
$V_{BE(Q)}$	Base-Emitter voltage of output transistor (Q) $I_{OL} = 16 \text{ mA}$, $I_X + I_{\bar{X}} = 0.41 \text{ mA}$, $R_{X\bar{X}} = 0$			1.1	V
V_{OH}	High-level output voltage $I_{OH} = -0.4 \text{ mA}$, $I_X = 0.15 \text{ mA}$, $I_{\bar{X}} = -0.15 \text{ mA}$	2.4	3.4		V
V_{OL}	Low-level output voltage $I_{OL} = 16 \text{ mA}$, $I_X + I_{\bar{X}} = 0.3 \text{ mA}$, $R_{X\bar{X}} = 114 \Omega$		0.2	0.4	V

electrical characteristics (SN7423 circuits) using expander inputs, $V_{CC} = 4.75 \text{ V}$, $T_A = 0^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$I_{\bar{X}}$	Expander current $V_{X\bar{X}} = 0.4 \text{ V}$, $I_{OL} = 16 \text{ mA}$			-3.8	mA
$V_{BE(Q)}$	Base-Emitter voltage of output transistor (Q) $I_{OL} = 16 \text{ mA}$, $I_X + I_{\bar{X}} = 0.62 \text{ mA}$, $R_{X\bar{X}} = 0$			1	V
V_{OH}	High-level output voltage $I_{OH} = -0.4 \text{ mA}$, $I_X = 0.27 \text{ mA}$, $I_{\bar{X}} = -0.27 \text{ mA}$	2.4	3.4		V
V_{OL}	Low-level output voltage $I_{OL} = 16 \text{ mA}$, $I_X + I_{\bar{X}} = 0.43 \text{ mA}$, $R_{X\bar{X}} = 130 \Omega$		0.2	0.4	V

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$, $N = 10$, (see note 3)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	$R_L = 400 \Omega$, $C_L = 15 \text{ pF}$		13	22	ns
t_{PHL}	$R_L = 400 \Omega$, $C_L = 15 \text{ pF}$		8	15	ns

NOTE 3: Switching characteristics of the SN5423 and SN7424 are tested with the expander pins open.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9763601QEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder

temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9763601QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J	Samples
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00403BCA	Samples
JM38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00403BCA	Samples
M38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00403BCA	Samples
M38510/00403BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00403BCA	Samples
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5425J	Samples
SN5425J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5425J	Samples
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN7423N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7425N	Samples
SN7425N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7425N	Samples
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7425N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7425N	Samples
SN7425NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7425N	Samples
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J	Samples
SNJ5423J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9763601QE A SNJ5423J	Samples
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI	-55 to 125		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ5423W	OBSOLETE			16		TBD	Call TI	Call TI	-55 to 125		
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5425J	Samples
SNJ5425J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5425J	Samples
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5425W	Samples
SNJ5425W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5425W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN5423, SN5425, SN7423, SN7425 :

- Catalog: [SN7423](#), [SN7425](#)
- Military: [SN5423](#), [SN5425](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com